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Advanced Storage Technology Consortium

Launch Event

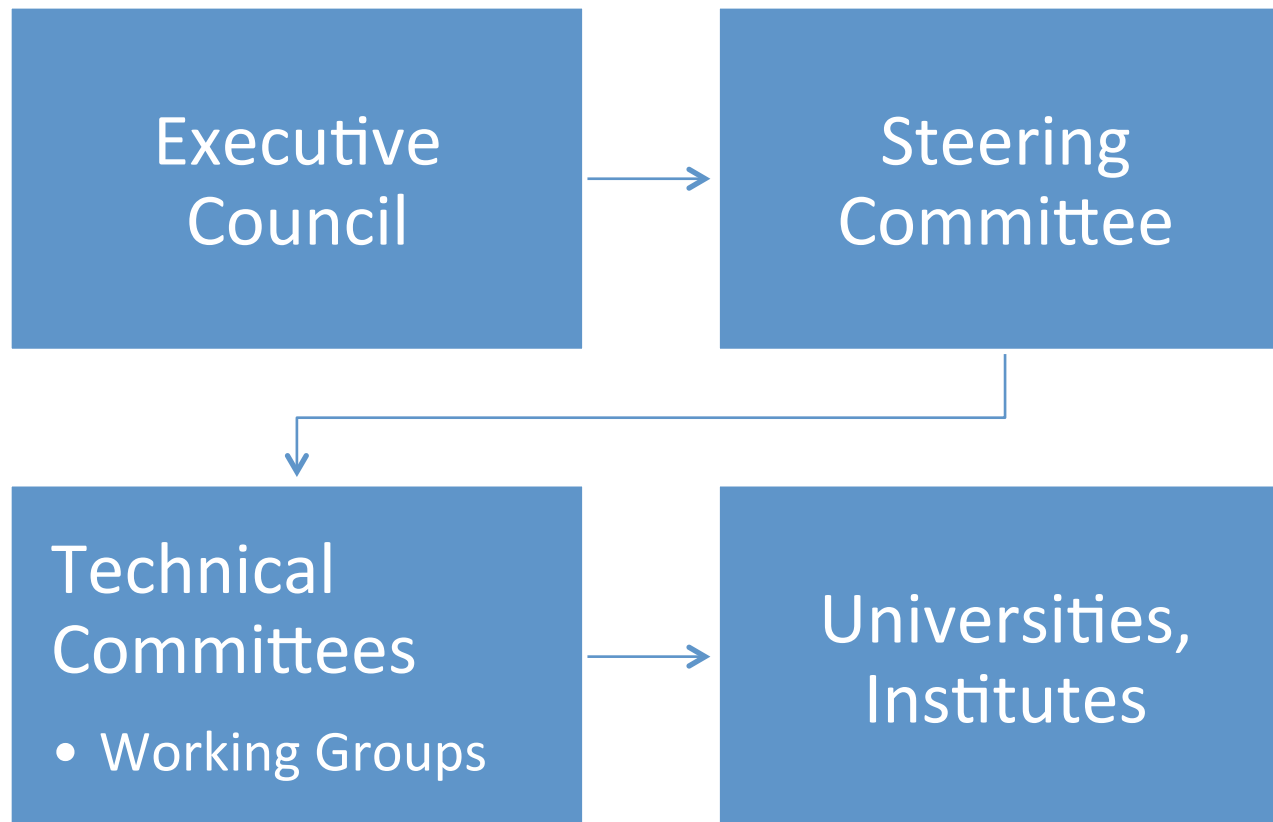
January 31 – February 1 2011

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- **Expanding and enhancing the power of R&D funding** and technology development between storage industry participants, suppliers, universities, laboratories, and institutes
- **Mission:** member-directed, scalable R&D organization to address – pro-competitively – fundamental technology challenges
- **Supply chain involvement**
- **HDD technology roadmap**

ASTC Structure



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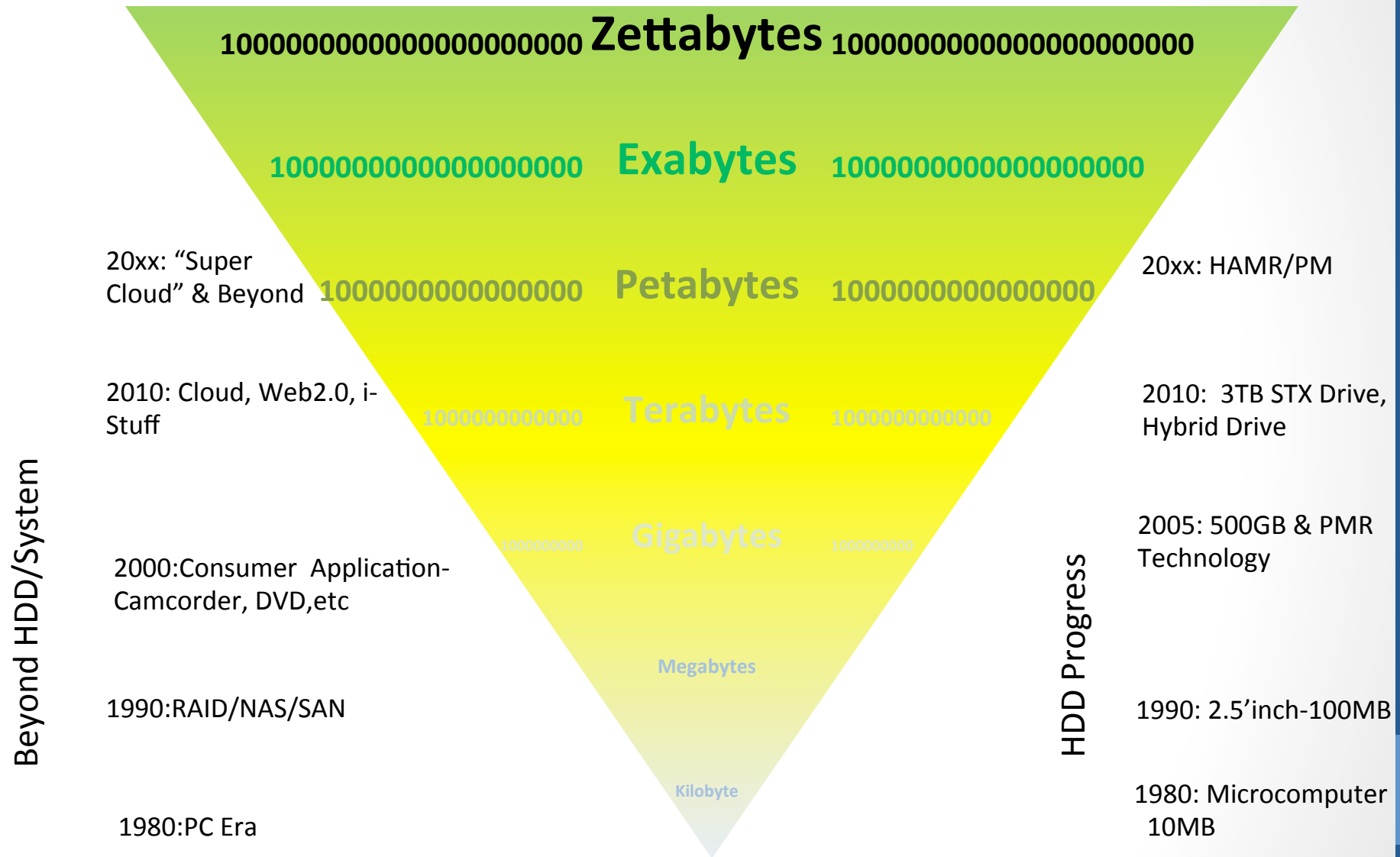


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Some Facts About Data Storage

HDDs and Growing Storage Demand



Fact 1: Consider That

**40 exabyte(10^{18}) of
Unique new
information will be
generated worldwide
this year**



Fact 3 : The Ever Expanding Growth of Information

**How Much Information?
2009
Report on American
Consumers**



**32GBs passes the human
eye every day
18 GB of Games
12 GB of Video
3 GB of Movies**



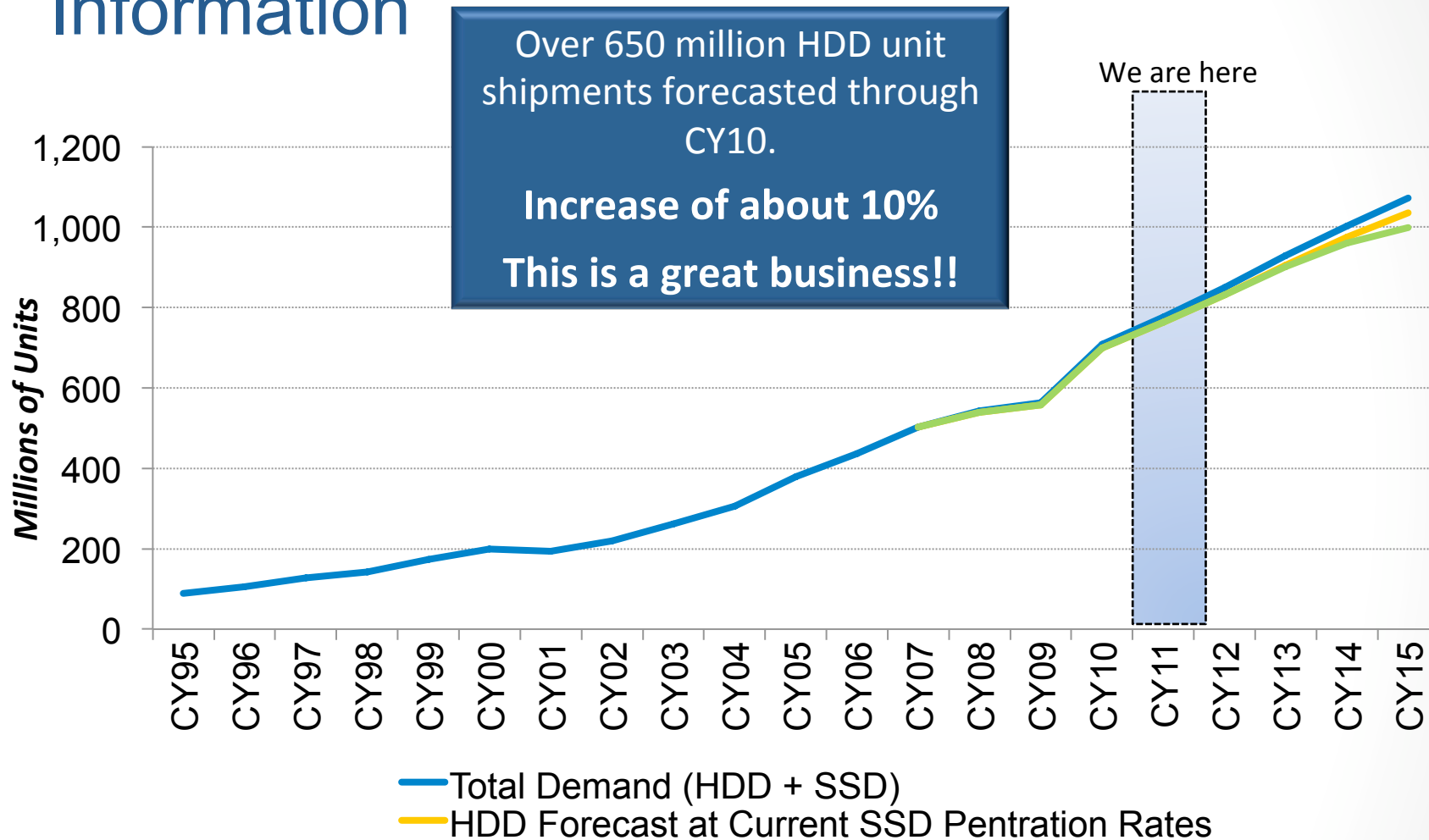
Sponsors:



Source: How Much Information? 2009 UCSD

Fact 4: The Need for HDDs to Store Information

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http://www.seagate.com/www/en-us/about/investor_relations/

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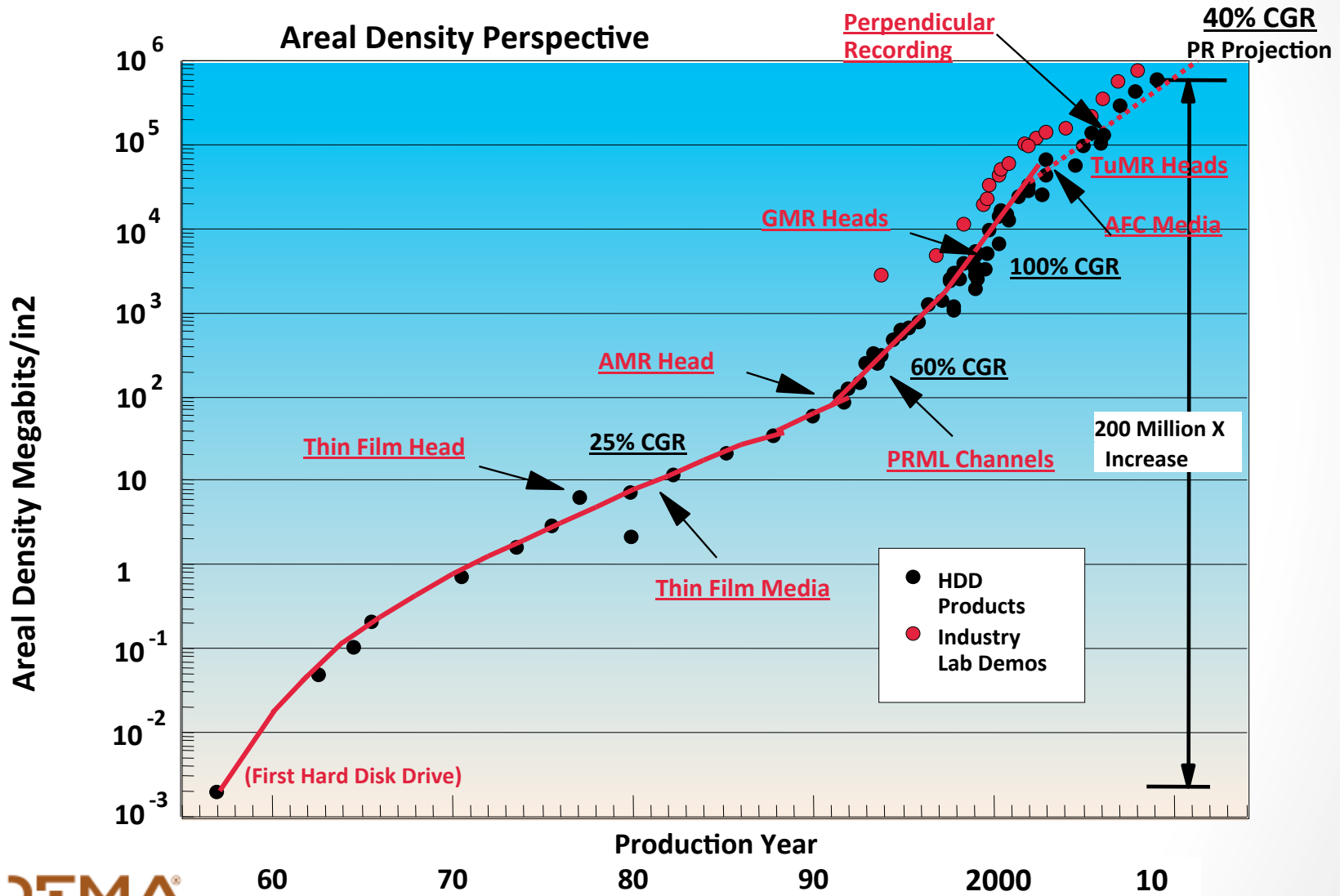

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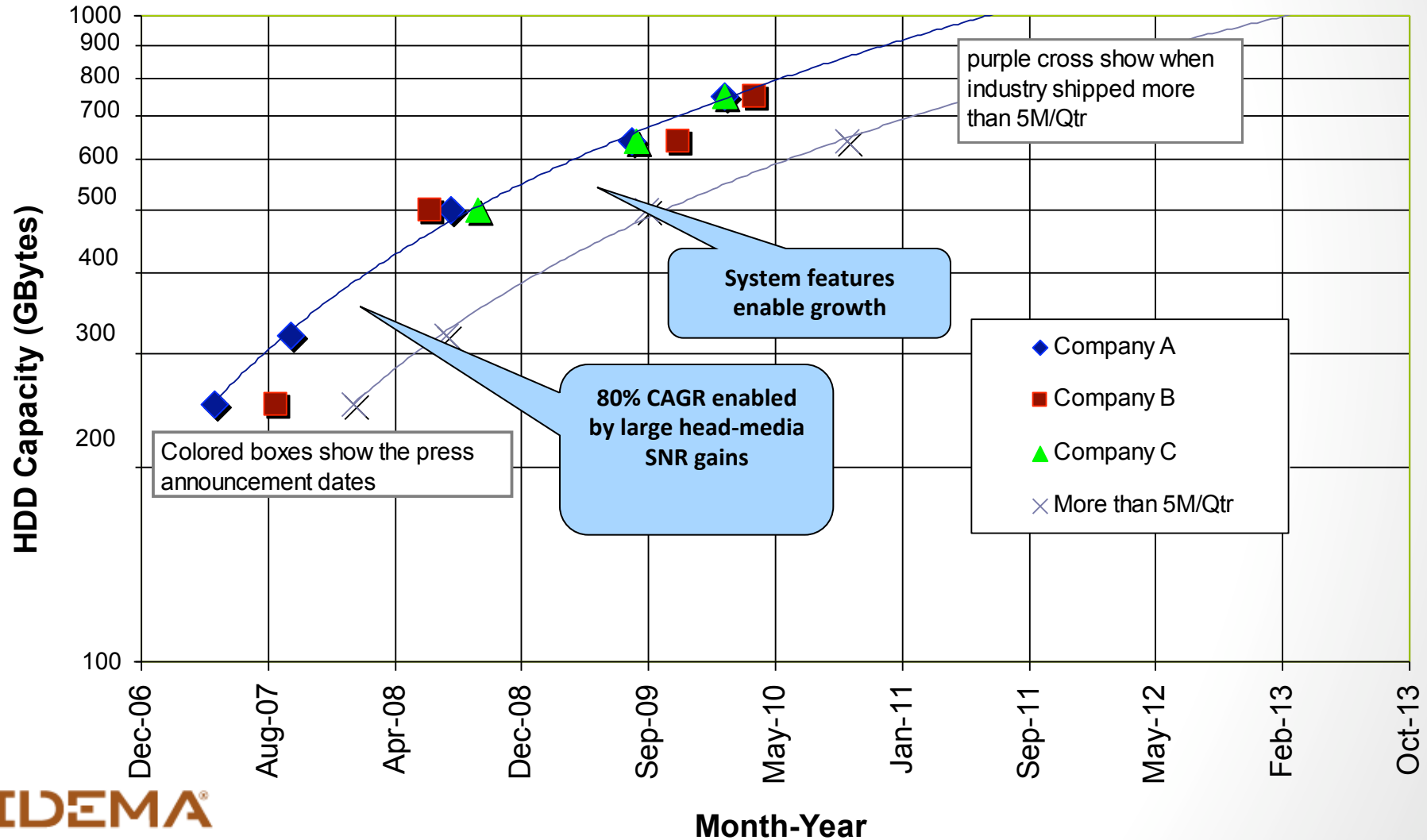
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HDD Industry Historical Areal Density Trend



Technology Maturity: Slowing PMR Capacity Growth Rate

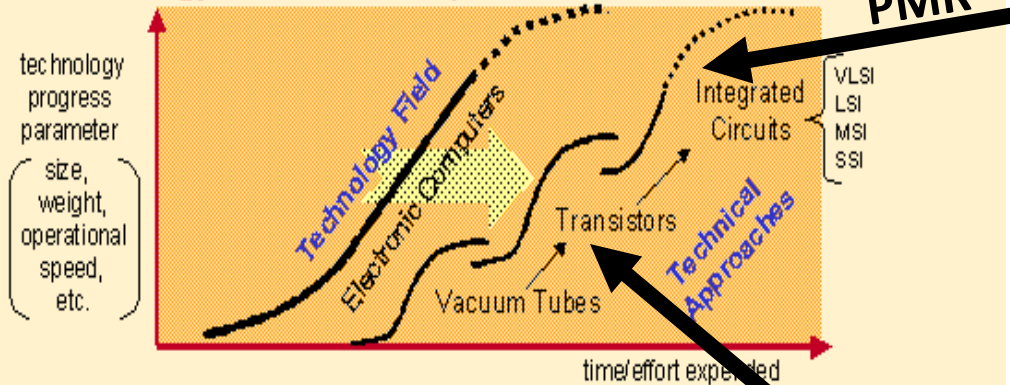
2 Disk Mobile Historical Announces With Volume Ship of > 5M/Qtr



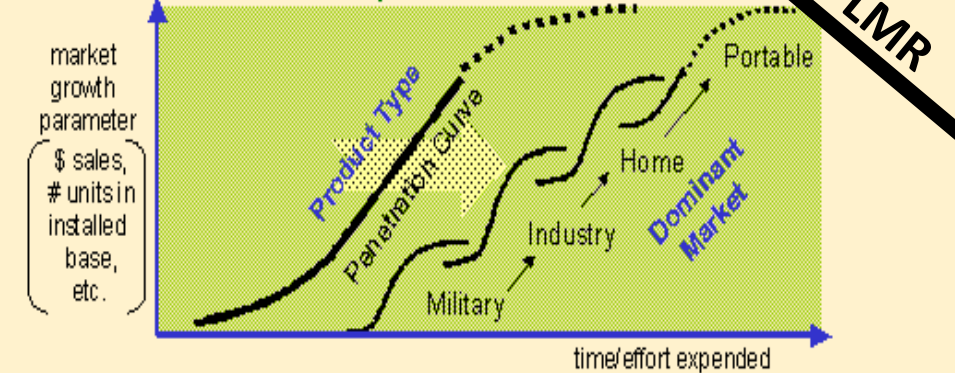
Historical Perspective: Jumping "S" Curves in HDD

S-Curve: Dynamics of Emerging Technologies & Markets

Technology S-Curve Development

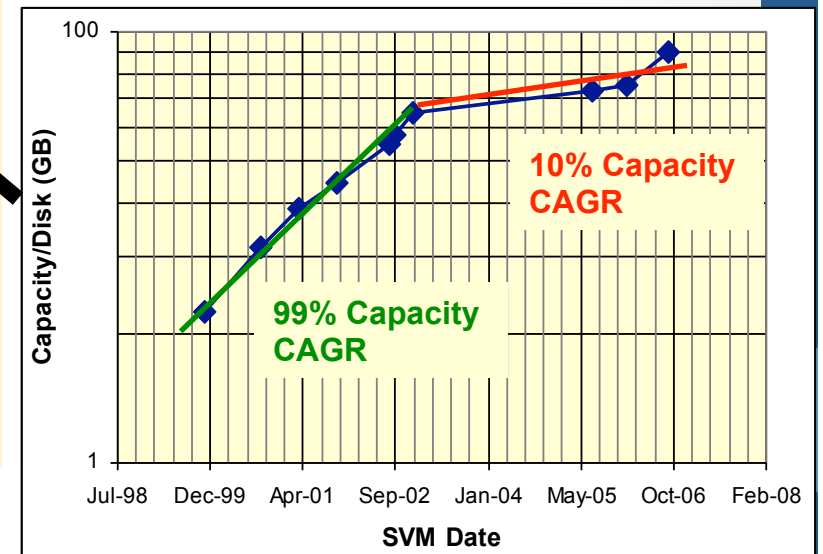
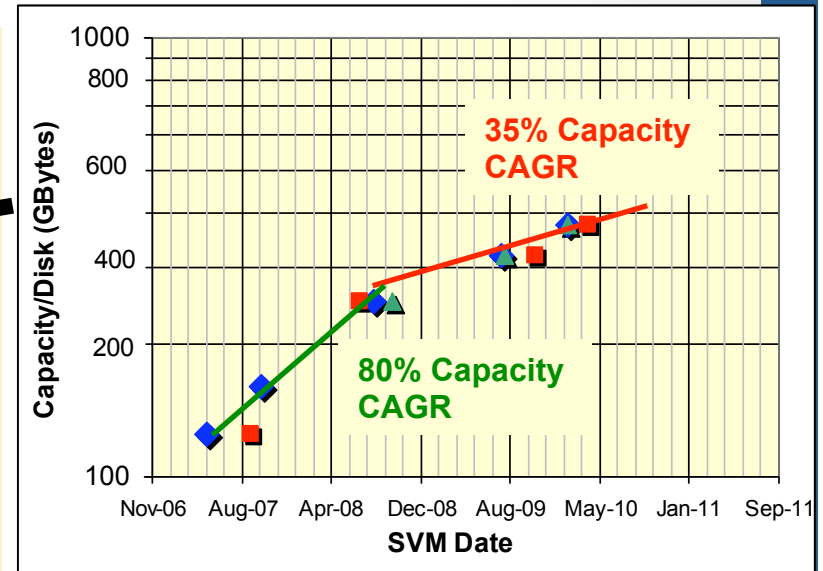


Market S-Curve Development



(after Afuah, A., OUP '98)

RSG: tfs curve 01a



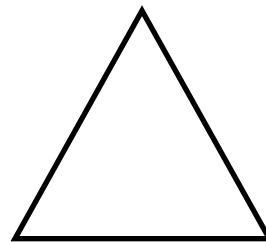
Areal Density Scaling and the Magnetic “Trilemma”

To preserve
signal-to-noise ratio:

$$\text{SNR} \sim \log_{10}(N)$$

the # of grains in a
bit must be
constant.

Signal-to-Noise Ratio



Thermal
stability

Writeability

In order to write a sharp recorded bit
transition, the write field needs to be
sufficiently large

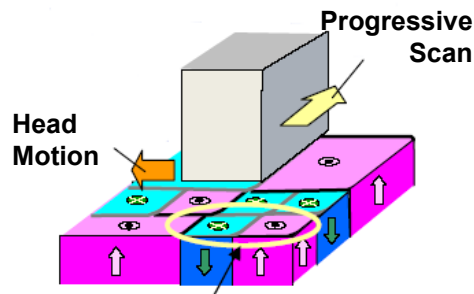
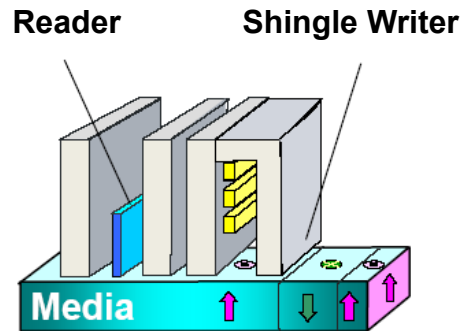
$$\text{Write Field} > \alpha \frac{2K_u}{M_s} - N_{\text{eff}} * M_s$$

To ensure that the recorded bit is
thermally stable, the anisotropy
needs to increase proportionally to
the grain volume reduction

$$\frac{\text{Stored Energy}}{\text{Thermal Energy}} \sim \frac{K_u * V}{k_B * T} > 70$$

Future Technology Options

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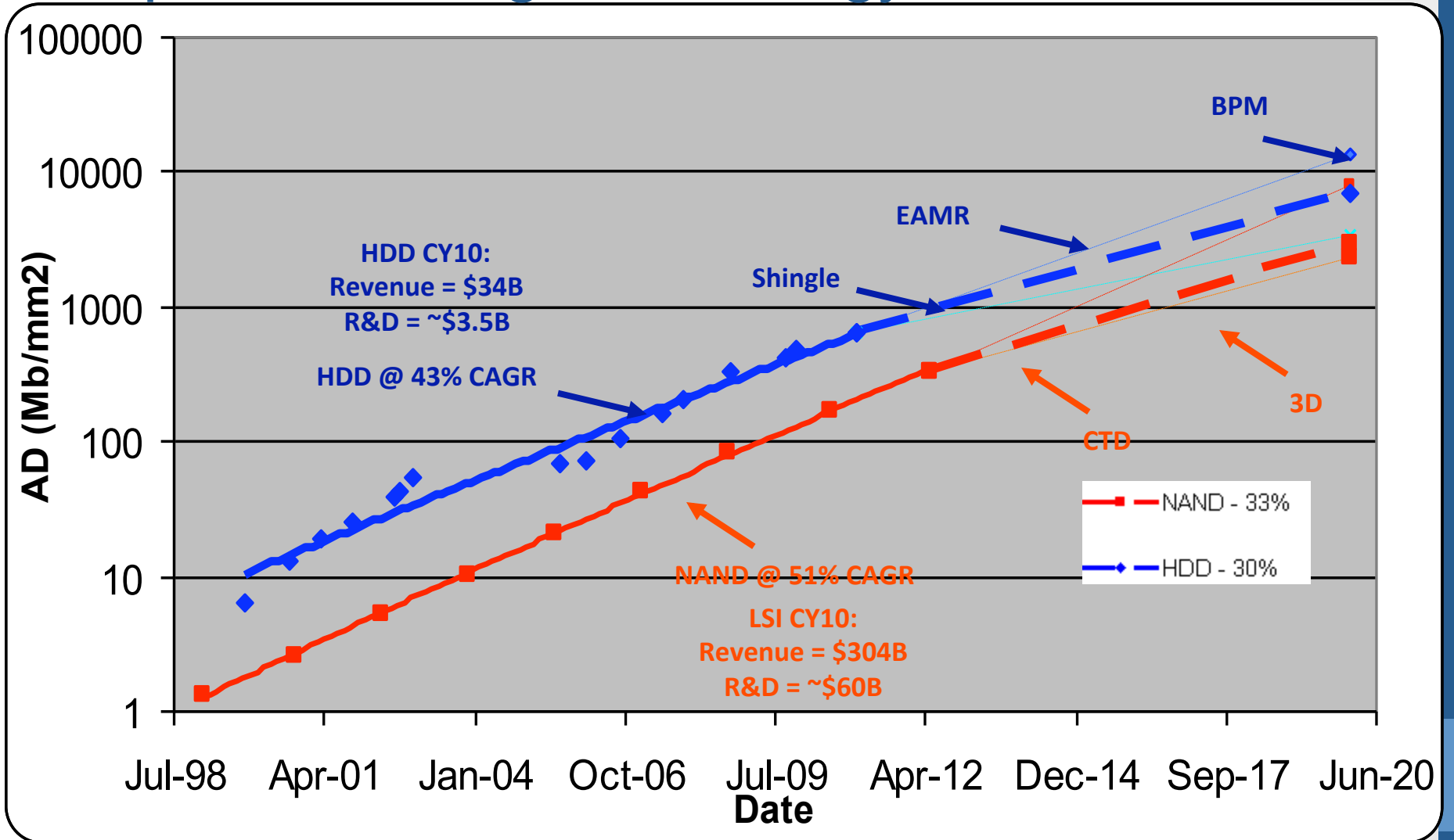


SMR/TDMR

- Continued scaling requires innovations in systems technologies, materials science and process engineering to advance areal density

Solid State Technology Memory as a Competitive Storage Technology

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ASTC Can Help Address HDD Technology Challenges

- HDD Industry is facing challenges to grow areal density at historic rates
- These challenges are distributed throughout component and system level technologies
 - Energy assist technology will not in itself enable AD growth without adequate readers, H/M interface, channel, servo capability, etc.
- Solid State Technology has emerged as a credible alternative to HDD in certain segments, and the semiconductor industry is committed to large scale R&D
- ASTC provides the ideal forum to address these challenges collaboratively as an industry with a holistic but targeted approach

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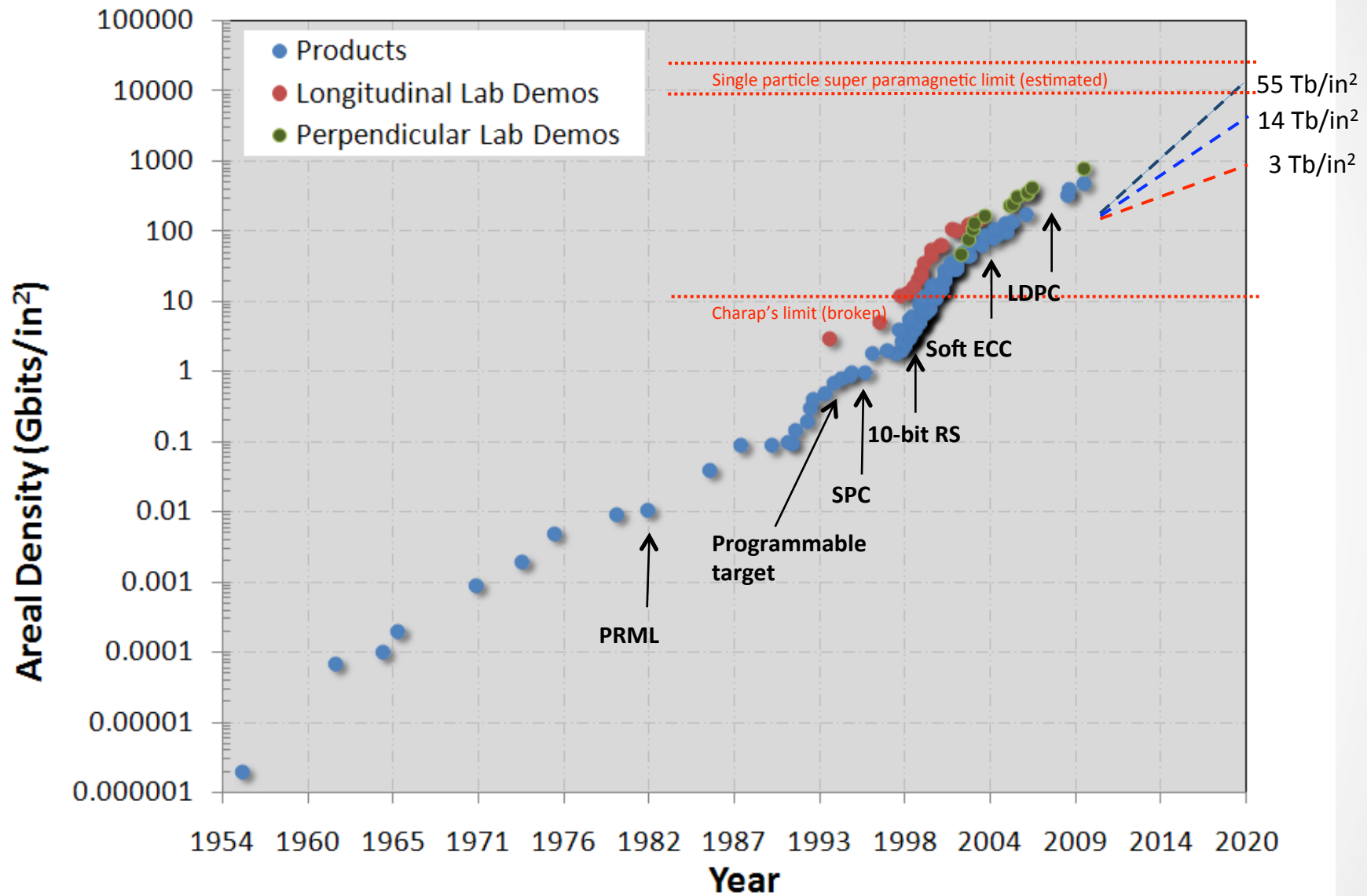
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Signal Processing Contribution to HDD Density Growth

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Recent Trends in Signal Processing

- SNR improvements coming from the Read Channel (RDC) were driven by advancements in Error Correction Coding (ECC): large codeword size afforded by adaptation of Long Sector Format, and transition to Soft ECC
- Shingled recording, Bit Pattern Recording (BPR), Two-Dimensional Magnetic Recording (TDMR), and Heat Assisted Magnetic Recording (HAMR) provide new challenges to signal processing
- Hard disk controller SOC should no longer be viewed as a standalone component in the drive; it has become an integral part of system solution.

Challenges Going Forward

- HDD is facing severe competition from SSD and other storage technologies
- HDD industry needs to collaborate to define a technology roadmap
 - A roadmap gives our industry more negotiation power with customers
- New technologies require more R&D investment and collaboration
 - Peak detectors have long been replaced by PRML with sophisticated detectors designed to take signal characteristics into account
 - Powerful iterative decoders come to replace traditional algebraic ECC's
 - Cutting-edge CMOS technology in electronics design is key to future success.
 - Leveraging some technologies used in solid state drives in support of large block write formats in SMR
 - Adding some level of non-volatile chip memory support for power-loss handling

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Why is the HDD supply base interested in ASTC?

Suppliers meet HDD Factories

- HDD producers operates at the outer boundaries of technology & scientific knowledge
- “There’s plenty of room at the bottom”[§]
 - *One nanometer is the characteristic dimension*
 - substrate processes, sputtering, chemistry, metrology
 - *Two million hours is the characteristic MTBF*
 - automation, disk processing systems, cleaning, RV
 - *Three gigahertz is the characteristic frequency*
 - SOC, control, interface
- Suppliers must meet producers needs at the outer boundaries of technology & scientific knowledge

Suppliers to HDD Producers

- Far-flung supply chain provides materials, components, manufacturing, processing, and test equipment:

- *substrates*
- *specialty metals*
- *sputtering systems*
- *automation*
- *cleaning systems*
- *processing equipment*
- *processing supplies*
- *certification*
- *dimensional metrology*

- *magnetic metrology*
- *optical metrology*
- *chemicals*
- *suspensions*
- *pre-amps*
- *channels*
- *SOC's*
- *servo track writers*
- **Supply Chain Goes On ...**

Benefits for Infrastructure Companies

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- “Early warning” to technology transitions
- Lead time to meet process and test requirements
- Roadmap alignment within the industry
 - drive, heads, media, electronics, mechanical components
- Roadmap alignment leads to efficient equipment development
 - Agreed-upon equipment platforms serving the industry
 - Efficient use of R&D resources developing equipment and process
 - Meet time-to-market need for advanced technology products and at lower cost

Partnership HDD/Supply

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Chain

- Improving areal density beyond ~ 1.5 Tb/in² likely will require a transition to new technology
- HDD producers & supply chain collaboration is essential:
 - To manage technology choices
 - To generate detailed technology roadmap
 - To provide guidelines for each of process areas and infrastructure development: “built for manufacturability & testability”
- The success of ASTC will:
 - Steer suppliers efforts and investments to HDD producers’ needs
 - Yield shared solutions in component technologies
 - Reduce technology risk and improve time-to-market

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So What is ASTC ?

Why Do We Need Something Different ?

- Pace of technology transitions and scope of change required means business as usual approach won't work
- Need to collimate and focus entire industry R&D to be successful
- Need coordinated transition in supply base -- components, equipment, and materials

Vision for New ASTC

- Global organization
- Learn and borrow from the successes of INSIC – EHDR and SRC programs
 - Collaborative research programs with universities
- More open collaboration among companies to share directions and manage projects
- Act with a sense of urgency consistent with the needs of the industry
- Engage broader base of companies

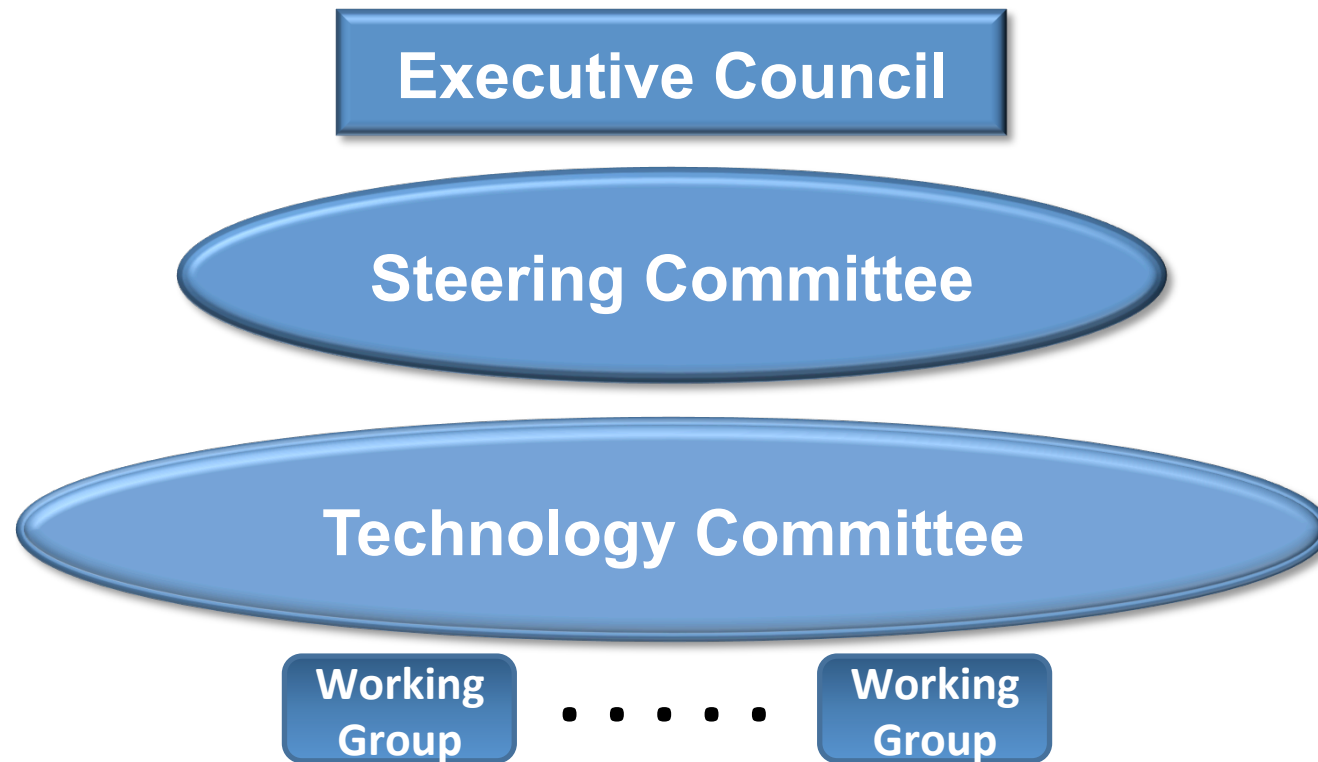
Expected Outputs from ASTC

- Forum to share and coordinate directions to increase speed and reduce waste
- Focused, collaborative research projects that will enable better understanding of key scientific challenges
- Shared, realistic roadmap for the Industry
- Solutions – **science** to **engineering** to **manufacturing** options – that will shorten time from invention to productization

What is Expected from Members ?

- Participation – commitment of time
- Openness – speed and reduce waste
- Higher funding levels
- More collaboration and direction setting in research projects

ASTC High Level Organization



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